

CXA2066S

Preamplifier for High Resolution Computer Display

Description

The CXA2066S is a bipolar IC developed for high resolution computer displays.

Features

- Built-in wide band amplifier: 140MHz @ -3dB (Typ.)
- Input dynamic range: 1.0Vp-p (Typ.)
- High gain preamplifier (17dB)
- R, G, and B incorporated in a single package
- I²C bus control

Contrast control Subcontrast control Brightness control OSD contrast control Cutoff control 4-channel DAC output 2 blanking level modes (0.5V fixed and Pedestal –0.6V) ABL control pin

- Built-in sync separator for Sync on Green
- Built-in blanking mixing function
- Built-in OSD mixing function
- Video period detection function
- Built-in sharpness function
- Built-in VBLK synchronous DAC refresh system

Applications

High resolution computer displays

Structure

Bipolar silicon monolithic IC

Absolute Maximum Ratings (Ta = 25°C, GND = 0V)

 Supply voltage 	Vcc	14	V
	Vcc2	7	V
 Operating temperature 	Topr	-20 to +75	°C
 Storage temperature 	Tstg	-65 to +150	°C
 Allowable power dissipation 	Pd	2.05	W

Recommended Operating Conditions

Supply voltage	Vcc	12 ± 0.5	V	
	Vcc2	5 ± 0.5	V	

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Block Diagram



Pin Description

Pin No.	Symbol	Pin voltage	Equivalent circuit	Description
1	SDA			I ² C bus standard SDA (serial data) input/output. VILMAX = 1.5V VIHMIN = 3.5V VOLMAX = 0.4V
2	SCL			I ² C bus standard SCL (serial clock) input. VILMAX = 1.5V VIHMIN = 3.5V
3 4 5 6	COF R COF G COF B COF RGB		$\begin{array}{c} \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\$	Cut-off adjustment DAC outputs. The output DC is 1 to 4V.
7 9 11	RIN GIN BIN	1.7V (when clamped)	7	RGB signal inputs. Input via the capacitor.
8	Vcc2	5V		5V power supply.

Pin No.	Symbol	Pin voltage	Equivalent circuit	Description
10	SYNC IN	2.8V		Sync on Green signal input. Input via the capacitor.
12	CLP		Vcc 10k 10k 12 777 777 777 777	Clamp pulse (positive polarity) input. VILMAX = 0.8V VIHMIN = 2.8V
13 14 15	OSD-R OSD-G OSD-B		Vcc 10k 10k 10k 10k 10k 10k 10k 10k	OSD control inputs. VILMAX = 0.8V VIHMIN = 2.8V
16	VDET		Vcc2 Vcc2 Vcc2 20k \$ 100 \$5k	Video detector output. Typ.; High = 4.3V Low = 0.2V

Pin No.	Symbol	Pin voltage	Equivalent circuit	Description
17	YS			YS (OSD_BLK) input. VILMAX = 0.8V VIHMIN = 2.8V
18	BLKING		Vcc Vcc 4k 4k 30k 10k 10k 7/77 7/77	Blanking pulse input. Set the V blanking pulse width to 300µs or more. VILMAX = 0.8V VIHMIN = 2.8V
19 23 26	GND-B GND-G GND-R	0V		GNDs.
20 24 27	BOUT GOUT ROUT		20 21 27 777 777 777 777 777 777 777 777 7	R, G, and B signal outputs.
21 25 28	S/H-B S/H-G S/H-R		21 28 777 28 777 28 777 777 777 7	Brightness sample-and-hold. Connect a capacitor to GND.
22	Vcc	12V		12V power supply.

Pin No.	Symbol	Pin voltage	Equivalent circuit	Description
29	ABL		29 Vcc Vcc Vcc 50k Vcc 50k Vcc 777 777 777 777 777	ABL control input. Ground to GND when not using ABL.
30	CSYNC		Vcc2 Vcc2 Vcc2 100 \$ 15k 30 777 777 777 777 777 777 777	Sync on Green signal sync separator output (positive polarity). Typ.; High = 4.3V Low = 0.2V

I²C BUS Register Definitions

Slave Address

SLAVE RECEIVER; 40 (HEX)

Register Table

SUB ADDRE	SS	BIT7	BIT7 BIT6 BIT5 BIT4 BIT3 BIT2 BIT1 BIT						BIT0
00H					CONT	RAST			
01H	I O BL			BRIGHTNESS					
02H					CUT (OFF R			
03H					CUT	OFF G			
04H				_	CUT	OFF B			
05H		VDET	LEVEL			OSD	GAIN		
06H					CUT OF	FF RGB			
07H					SUB CON	ITRAST R			
08H					SUB CON	ITRAST G			
09H					SUB CON	ITRAST B			
0AH		V DET OFF	SHP OFF	SYNC OFF	тsw		SHP	GAIN	
Sub Address 0001	BLK	MODE (1)	be a COI 0 2 Swi 0 1	adjusted by NTRAST. : Gain minii 55: Gain mi tches the bl : Pedestal - : 0.5V fixed	SUB CONT mum (–30dł aximum (+1 lanking leve -0.6V	rRAST and 3 or less) 7dB) I.	the luminal	nce can be	adjusted by
Sub Address 0001	BRI	GHTNESS	(6) Cor 0 6	Controls the black level common for the R, G, and B channels. 0: Black level minimum (1V) 63: Black level maximum (3V)					S.
Sub Address CUT OFF R (8) 0010			Cor 0 2	ntrols Pin 3 : Output vo 55: Output	(COF R) ou Itage minim voltage max	tput voltage um (1V) kimum (4V)	s.		
Sub Address CUT OFF G (8) 0011			Cor 0 2	Controls Pin 4 (COF G) output voltage. 0: Output voltage minimum (1V) 255: Output voltage maximum (4V)					
Sub Address 0100	CUT	「OFF B (8)	Cor 0 2	Controls Pin 5 (COF B) output voltage. 0: Output voltage minimum (1V) 255: Output voltage maximum (4V)					

Sub Address 0101	VDET LEVEL (2)	Controls the signal detection (VDET) slice level. 0: Slice level minimum (30mV when RIN = GIN = BIN) 3: Slice level maximum (220mV when RIN = GIN = BIN)
Sub Address 0101	OSD GAIN (6)	Controls the OSD gain common to the R, G, and B channels. Since control is performed by multiplying with SUB CONTRAST (upper 6 bits), white balance and tracking for the video is obtained. 0: Gain minimum (0Vp-p) 63: Gain maximum (5Vp-p)
Sub Address 0110	CUT OFF RGB (8)	Controls Pin 6 (COF RGB) output voltage. 0: Output voltage minimum (1V) 255: Output voltage maximum (4V)
Sub Address 0111	SUB CONTRAST R (8)	Controls the R channel gain. Control is performed by multiplying with CONTRAST. Use for adjusting the white balance. 0: Gain minimum (–30dB or less) 255: Gain maximum (+17dB)
Sub Address 1000	SUB CONTRAST G (8)	Controls the G channel gain. Control is performed by multiplying with CONTRAST. Use for adjusting the white balance. 0: Gain minimum (–30dB or less) 255: Gain maximum (+17dB)
Sub Address 1001	SUB CONTRAST B (8)	Controls the B channel gain. Control is performed by multiplying with CONTRAST. Use for adjusting the white balance. 0: Gain minimum (–30dB or less) 255: Gain maximum (+17dB)
Sub Address 1010	VDET OFF (1)	Controls the Pin 16 (VDET) output. 0: VDET output on 1: VDET output off
Sub Address 1010	SHP OFF (1)	Controls the sharpness function. 0: Sharpness on 1: Sharpness off
Sub Address 1010	SYNC OFF (1)	Controls the Pin 30 (CSYNC) output. 0: SYNC output on 1: SYNC output off
Sub Address 1010	T SW (1)	Controls the time constant during sharpness. 0: 50ns 1: 100ns
Sub Address 1010	SHP GAIN (4)	Controls the sharpness gain. 0: Gain minimum (–30dB or less) 15: Gain maximum (+7dB)

Electrical Characteristics

No.	Measurement item	Symbol	Measurement contents	Min.	Тур.	Max.	Unit
1	Current	lcc1	Vcc and Vcc2 pins inflow current	65	88	110	mA
	consumption	lcc2	Input signal: None	30	45	60	mA
2	Frequency response (50MHz)	F4	Input continuous 1MHz, 50MHz, and 100MHz sine waves at 0.7Vp-p. Measure the output amplitude gain difference at this time. Gain difference [dB] = 20 log $\left(\frac{V_{OUT} 50M}{V_{OUT} 1M}\right)$ Gain difference [dB] = 20 log $\left(\frac{V_{OUT} 100M}{V_{OUT} 1M}\right)$	-1.7	0	1.7	dB
	Frequency response (100MHz)	F5	RGB input signal (RGB input pins)	-5.5	-1.85	1.8	
	Contrast control 1	GCONT1	Measure the level of the output signal amplitude Vout when a 0.7Vp-p video signal is input. (ABL = 0V) VCONT1: Contrast = Sub Contrast = FF VCONT2: Contrast = 00/Sub Contrast = FF	4.5	5.0	5.5	Vp-р
5	Contrast control 2	GCONT2	Input signal	-30	35	100	mVp-p
4	Sub Contrast control	GSUB	Measure the level of the output signal amplitude Vout when a 0.7Vp-p video signal is input. (Contrast = FF/Sub Contrast = 00/ ABL = 0V) Input signal	-30	35	100	mVp-p

No.	Measurement item	Symbol	Measurement contents	Min.	Тур.	Max.	Unit	
5	OSD gain control	GOSD1	Measure the OSD level of the output signal when an OSD pulse is input. GOSD1: OSD = 3F/Sub Contrast = FF GOSD2: OSD = 00/Sub Contrast = FF RGB output signal	4.4	5.0	5.6	Vp-p	
		GOSD2		-240	-70	80	mVp-p	
6	Brightness control	Brightness	VBRT1	Measure the black level of the RGB output signal. VBRT1: Brightness = 00 VBRT2: Brightness = 3F RGB output signal	0.8	1.1	1.4	V
		VBRT2	Black level	2.65	2.9	3.15	v	
7	BLK control (BLK MODE = 0)	VBLK1	Measure the BLK level of the output signal when a BLK pulse is input.	400	560	720	۳V	
	BLK control (BLK MODE = 1)	VBLK2	BLK level (VBLK1) BLK level (VBLK2) GND	200	310	420	ΠV	

No.	Measurement item	Symbol	Measurement contents	Min.	Тур.	Max.	Unit
	Sharpness gain 1	SHP1	Input a 30MHz sine wave to RGB at an amplitude of 0.1Vp-p, and measure the output level, and then calculate I/O gain.	8.9	10.9	12.9	
0	Sharpness gain 2	SHP2	Gain difference [dB] = $20 \log \left(\frac{Output level}{Input level} \right)$ (Contrast = 7F/Sub Contrast = FF/ ABL = 0V) SHP1: SHP GAIN = 0/T SW = 0	14.6	16.6	18.6	
8	Sharpness gain 3	SHP3	SHP2: SHP GAIN = F/T SW = 0 SHP3: SHP GAIN = 0/T SW = 1 SHP4: SHP GAIN = F/T SW = 0 Input signal	9.2	11.2	13.2	aв
	Sharpness gain 4	SHP4	GND CLP potential (approximately 1.7V)	16.3	18.3	20.3	
9	Input D range (VIN = 0.7V)	VIND1	Measure the output level when 0.7Vp-p and 1.2Vp-p input video		4.3	4.8	Vo-n
	Input D range (VIN = 1.2V)	VIND2	(Contrast = CC, Sub Contrast = FF, Brightness = 00)	5.8	6.3	6.8	۸۵-۵
10	SYNCSEP output high level	SYNCHI	Input a Sync on Green video signal to SYNCIN, and measure the CSYNC high level and low level.	4.1	4.4	4.7	V
	SYNCSEP output low level	SYNCLO	CSYNCHigh level GNDLow level	100	200	300	mV
11	SYNCSEP output rise delay	SDLYR	Input signal		42	50	20
	SYNCSEP output fall delay	SDLYF	CSYNC Vth = 50%		45	70	GII I

No.	Measurement item	Symbol	Measurement contents	Min.	Тур.	Max.	Unit
12	VDET output high level	VDETHI	Measure the VDET high level and low level when a 0.7Vp-p video signal is input to RGB.	4.1	4.4	4.7	V
	VDET output low level	VDETLO	VDET High level Low level	200	280	400	mV
13	VDET output rise delay	VDDLYR	Input signal Vth = 50%		17	40	25
	VDET output fall delay	VDDLYF	VDET Vth = 50%		26	50	115
14	DAC output voltage (COFF = 00)	VCUT1	Measure the DAC output voltage (Pins	0.9	1.1	1.3	V
	DAC output voltage (COFF = FF)	VCUT2	3, 4, 5, and 6) when COFF = 00/FF.	3.8	4	4.2	v

I²C BUS Logic System

No.	Item	Symbol	Min.	Тур.	Max.	Unit
1	High level input voltage	Viн	3.0	_	5.0	V
2	Low level input voltage	VIL	0	_	1.5	V
3	Low level output voltage SDA, during current inflow of 3mA	Vol	0		0.4	V
4	Maximum clock frequency	fsc∟	0	—	100	kHz
5	Minimum waiting time for data change	t buf	4.0	—	—	μs
6	Minimum waiting time for data transfer start	tнd; STA	4.0	_	_	μs
7	Low level clock pulse width	tLOW	4.7	_	_	μs
8	High level clock pulse width	tнigн	4.0	_	_	μs
9	Minimum waiting time for start preparation	tsu; STA	4.7	_	_	μs
10	Minimum data hold time	tнd; DAT	440	_	_	ns
11	Minimum data preparation time	tsu; DAT	250	_	_	ns
12	Rise time	t R	_	_	1	μs
13	Fall time	t⊧		_	300	ns
14	Minimum waiting time for stop preparation	tsu; STO	4.7	—	_	μs

Electrical Characteristics Measurement Circuit





Electrical Characteristics Measurement Circuit (Frequency Response)

Description of Operation

1. Sharpness function

The RGB signals input to Pins 7, 9, and 11 are mixed at a ratio of 0.6G + 0.3R + 0.1B to form the Y signal. The high-frequency component is removed from this Y signal by a differentiation circuit, and the amplitude is controlled by a gain control circuit. The signal which undergoes gain control (sharpness component) has its amplitude clipped by a limiter circuit and is then added to the R, G, and B signals.



2. VBLK synchronous DAC refresh system

The VBLK signal is removed from the composite BLK signal which has been input to Pin 18, and the data for each control DAC is overwritten all at once in synchronization with this VBLK signal. The received I²C bus data is held by a latch until the next VBLK signal arrives. As a result, I²C bus data transmission from the microcomputer is timing-free. Set the V blanking pulse width which is input to Pin 18 at 300µs or more.



Application Circuit



Application circuits shown are typical examples illustrating the operation of the devices. Sony cannot assume responsibility for any problems arising out of the use of these circuits or for any infringement of third party patent and other right due to same.

Example of Representative Characteristics





Notes on Operation

- 1. Set the output for ROUT, GOUT, and BOUT for reception at high impedance.
- 2. Make the wiring from ROUT, GOUT, and BOUT to the power amplifier as short as possible.
- 3. Connect the Vcc and Vcc2 decoupling capacitor so that the ceramic capacitor and electrolytic capacitor are connected in parallel and the distance from the IC is as short as possible.
- 4. Connect the clamp capacitor for RIN, GIN, BIN, S/H-R, S/H-G, S/H-B so that the distance from the IC is as short as possible.
- 5. Set the output to OFF when the VDET output is not used (Set I²C BUS VDETOFF "1").

Package Outline Unit: mm

30PIN SDIP (PLASTIC)



SONY CODE	SDIP-30P-01
EIAJ CODE	SDIP030-P-0400
JEDEC CODE	

MOLDING COMPOUND	EPOXY RESIN
LEAD TREATMENT	SOLDER/PALLADIUM PLATING
LEAD MATERIAL	COPPER ALLOY
PACKAGE MASS	1.8g

NOTE : PALLADIUM PLATING This product uses S-PdPPF (Sony Spec.-Palladium Pre-Plated Lead Frame).